

In the upcoming Electronica Exhibition Densitron will unveil its new Bonding facility, proprietary E-paper Evaluation Kit and RipDraw Display & Design Solution



London, Wednesday 26

September 2012: In the upcoming Electronica Exhibition, Densitron's proprietary E-paper Evaluation Kit and RipDraw Display and Design Solution will be unveiled. These new offerings promise to significantly reduce product development time and cost. Densitron will also introduce its new optical bonding facility and capability to add cover lenses or PCTs to any display using a reworkable process.

The new RipDraw introduction includes the worldwide launch of Densitron's Cloud Computing Web Portal. The portal enhances customers' ability to rapidly prototype world class GUI designs for TFT projects. Not only does the portal include a 7 layer intuitive WYSIWYG Drawing tool, it also comes fully populated with over 8,000 copyrighted royalty-free images for customers to use with the RipDraw™ TFT product line. This removes the barrier most mid-market customers confront if they lack the art department to fully utilize a TFT display. This coupled with the release of the RipDraw™ TFT emulator and initial release of the RipDraw™ 7" WVGA 1024 x 600 GPU assisted TFT display greatly reduces time to market and results in extraordinary cost effective GUI solutions for our customers.

New E-paper Evaluation Kits will be launched for screen sizes of 1.44", 2.0" and 2.7". Each kit comes with a controller board and a data and power board. The latter board receives data and power from PC USB interface and supplies data and power to the controller board via a UART or SPI interface.

The Densitron Bonding facility is located in Taiwan and uses state of the art Japanese Bonding technology to provide quality and cost-effective bonding solutions.

In addition to new product introduction, Densitron will demonstrate its extensive technical expertise on OLEDs, covering Monochrome, Full Colour and Alphanumeric modules with various interface options and development kits. Industrial grade cost-effective LCD modules and TFT displays with impressive optical parameters will also be showcased.

For applications that require enhanced displays, Densitron offers Engineering

In the upcoming Electronica Exhibition Densitron will unveil its new Bonding

Published on Electronic Component News (<http://www.ecnmag.com>)

Design Service (EDS) which offers options on integrating standard or custom display modules with PCB, Plastics, Keypads and/or Touch Overlays.

Visitors to Densitron's Booth A3.251 will be able to sample the latest display technologies and design solutions available today and to see product examples from Densitron's bonding service and Engineering Design projects.

Dedicated representatives from Densitron's technical support team will be present to provide assistance with choosing the right display and to offer advice on display integration.

Explore Densitron's exciting range of products today at: www.Densitron.com/Displays [1]

Source URL (retrieved on 01/29/2015 - 1:49pm):

http://www.ecnmag.com/products/2012/10/upcoming-electronica-exhibition-densitron-will-unveil-its-new-bonding-facility-proprietary-e-paper-evaluation-kit-and-ripdraw%E2%84%A2-display-design-solution?qt-recent_content=0

Links:

[1] <http://www.Densitron.com/Displays>